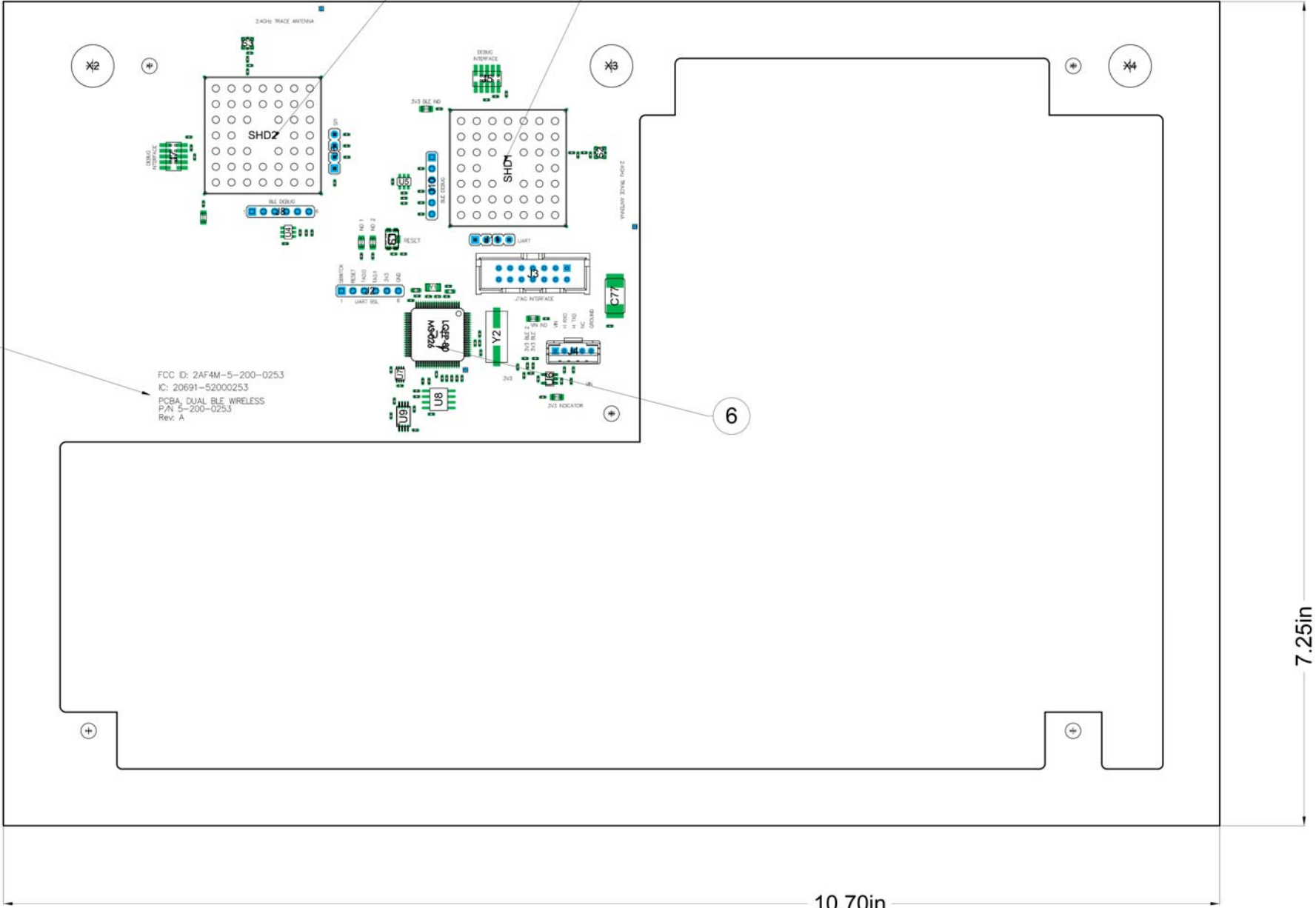
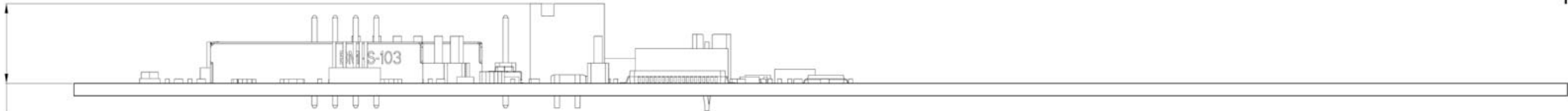


1. Assemble and Solder Per IPC-A-610 Class 2, RoHS Compliant Process.
2. Assembly to be Packaged and Transported. To be permanently marked in the appropriate area on the primary side of assembly.
3. Assembly to be packaged and transported in a conductive and shielded container and handled in a static safe work area
4. BOM for this assembly is released in Agile by the same part number and revision level
5. Board Serial Number Label to be applied at this location. Orientation as indicated. Each board shall have a new Serial Number and corresponding bar code to be placed under the board S/N.
6. Program U1 with programming file attached to 5-200-XXXX. Verify that the label on U1 states VX.XX.
7. Program SDH1 and SDH2 with programming file attached to 5-200-XXXX. Verify that the label on U1 states VX.XX.
8. Following Text needs to be in the top silkscreen:  
FCC ID: 2AF4M-5-200-0253  
IC: 20691-52000253

Revision History			
Rev	Description	Date	Approved
A	Initial Release	6/12/18	K. Lynn



View from Left side (Scale 2.7753)



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UNLESS OTHERWISE SPECIFIED:		NAME	DATE	Midmark Corporation	
DIMENSIONS ARE IN INCHES		DRAWN	6/12/2018	TITLE	
TOLERANCES:		CHECKED		PCBA, Dual BLE Wireless	
FRACTIONAL ±		ENG APPR.		Q.A.	
ANGULAR: MACH ±		Q.A.		COMMENTS	
TWO PLACE DECIMAL ±				SIZE	
THREE PLACE DECIMAL ±				DWG. NO.	
INTERPRET GEOMETRIC TOLERANCING PER:				REV	
MATERIAL				A	
NEXT ASSY		USED ON	FINISH	SCALE	
APPLICATION		DO NOT SCALE DRAWING		1:1	
				WEIGHT:	
				SHEET 1 OF 1	